



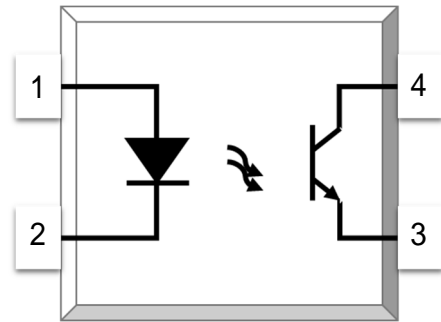
Description

Features

Applications

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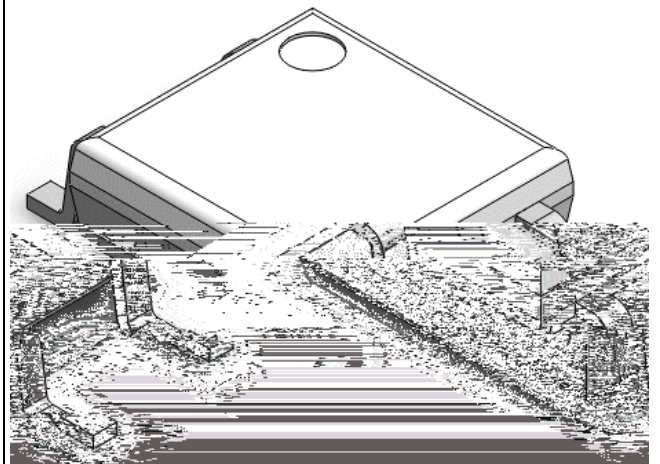
### SCHEMATIC



### PIN DEFINITION

1. Anode
2. Cathode
3. Emitter
4. Collector

### PAC A!E O" T#INE





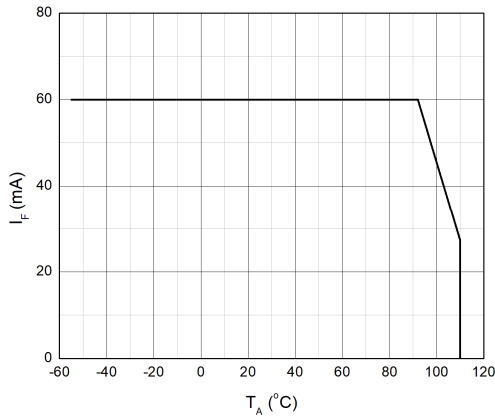
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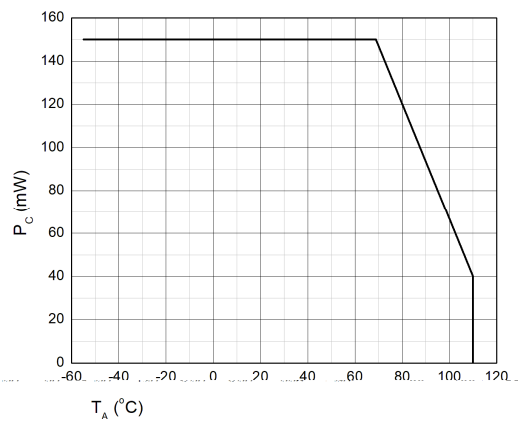


## CHARACTERISTICS - ES

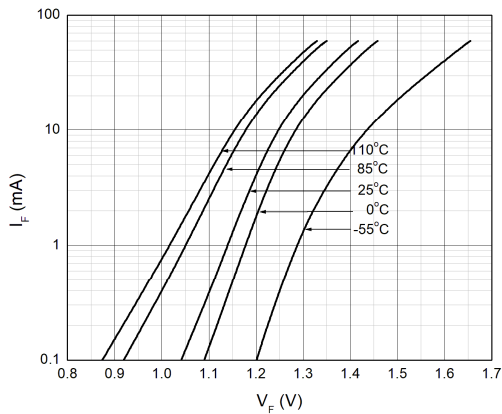
**Fig. 1 Forward Current vs. Ambient Temperature**



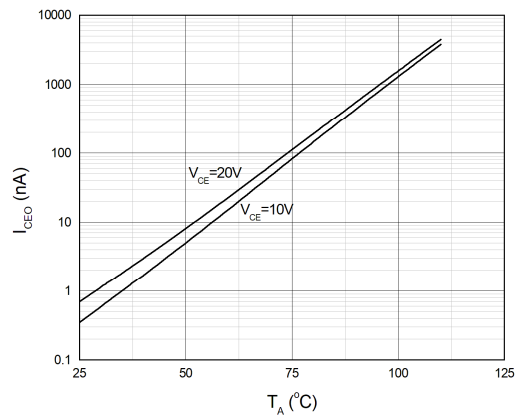
**Fig. 2 Collector Power Dissipation vs. Ambient Temperature**



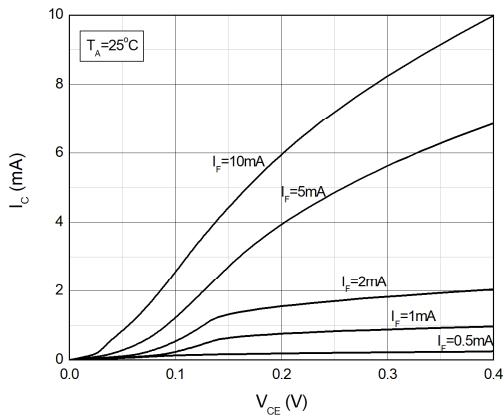
**Fig. 3 Forward Current vs. Forward Voltage**



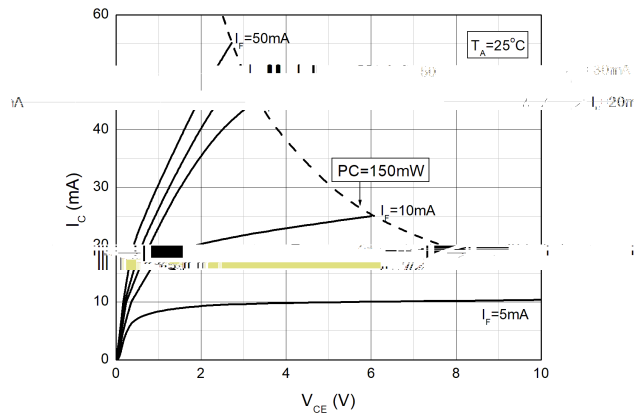
**Fig. 4 Collector Current vs. Ambient Temperature**



**Fig. 5 Collector Current vs. Collector-Emitter Voltage**



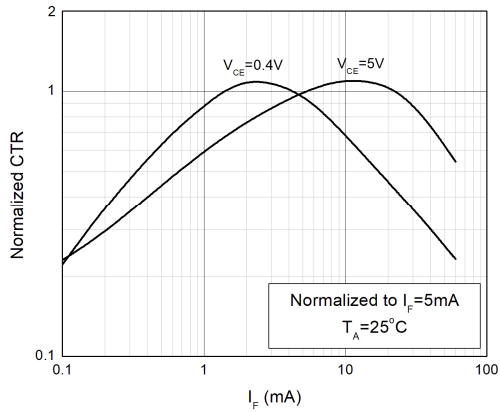
**Fig. 6 Collector Current vs. Collector-Emitter Voltage**



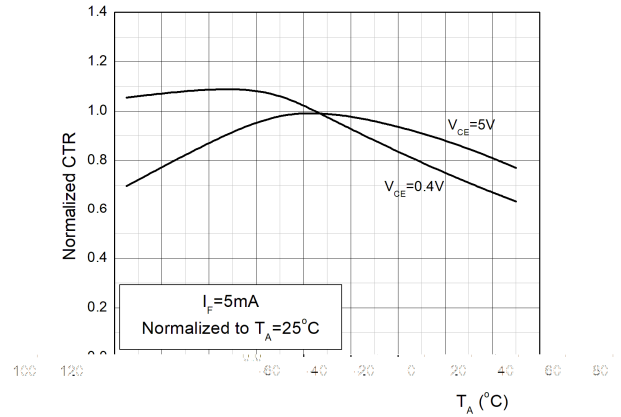


## CHARACTERISTIC CURVES

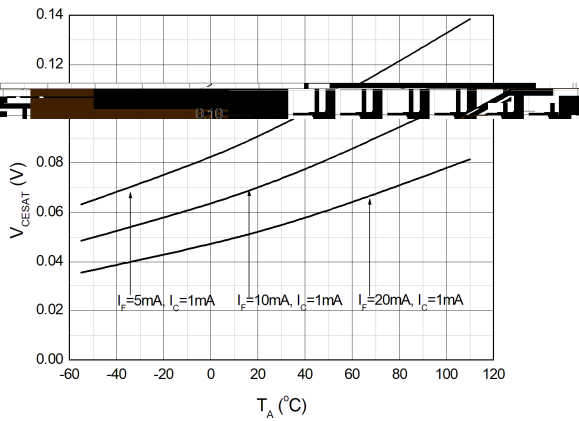
**Fig. 5 Normalized Current Transfer Ratio vs. Base Current**



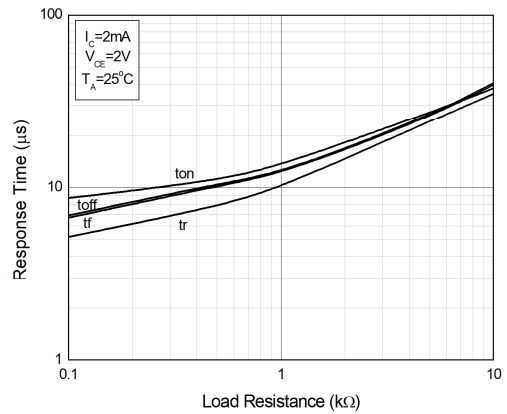
**Fig. 8 Normalized Current Transfer Ratio vs. Ambient Temperature**



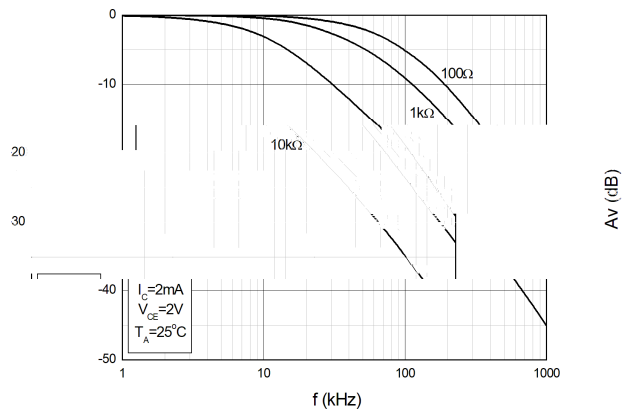
**Fig. 9 Collector-Emitter Saturation Voltage vs. Ambient Temperature**



**Fig. 10 Switching Time vs. Load Resistance**



**Fig. 11 Frequency Response**





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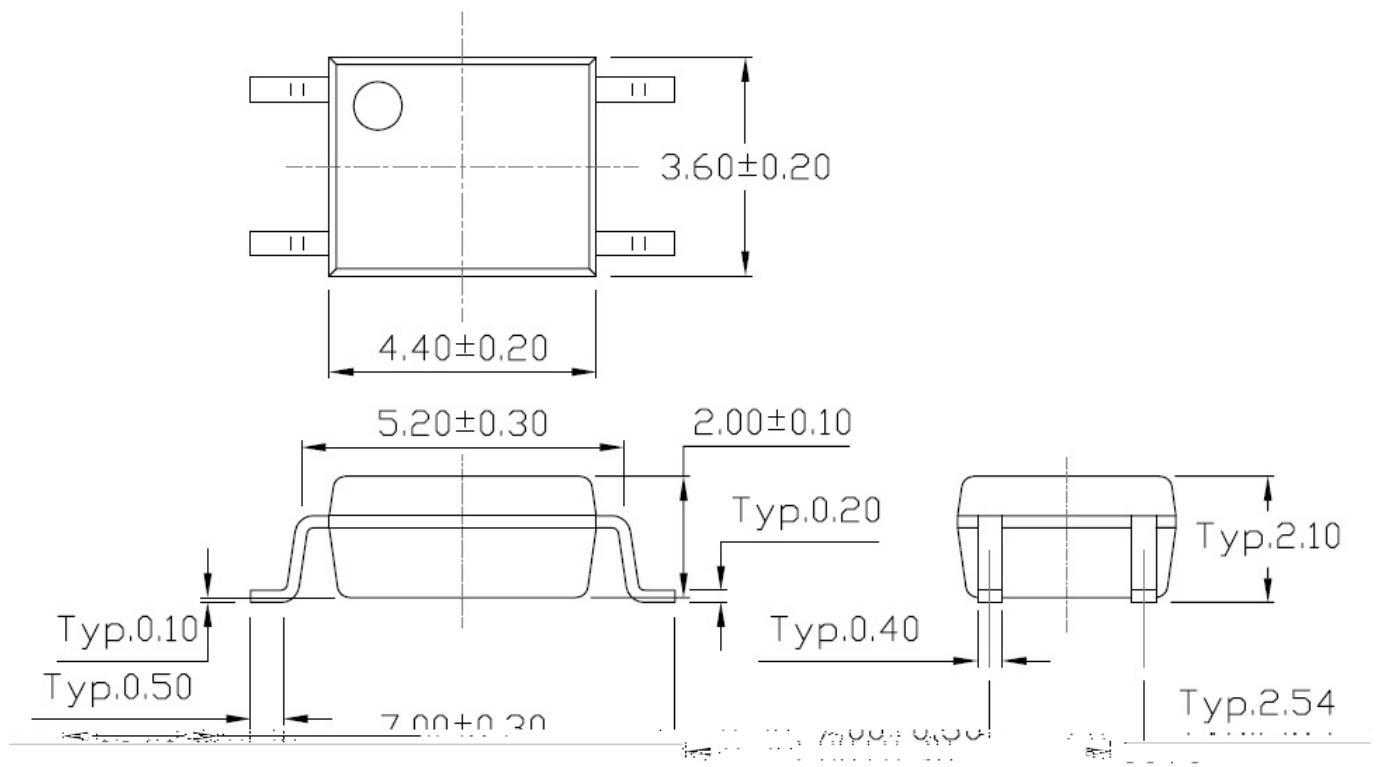
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## TEST CIRCUITS

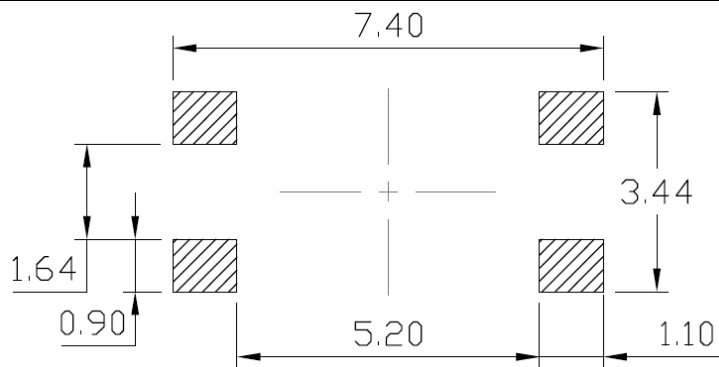
Fig. 12 Test Circuit of the Time

Fig. 13 Circuit of the Time

**PAC A ! E DIMENSIONS (Dimension\$ in mm & nle\$\$ other / i\$e \$tated=**

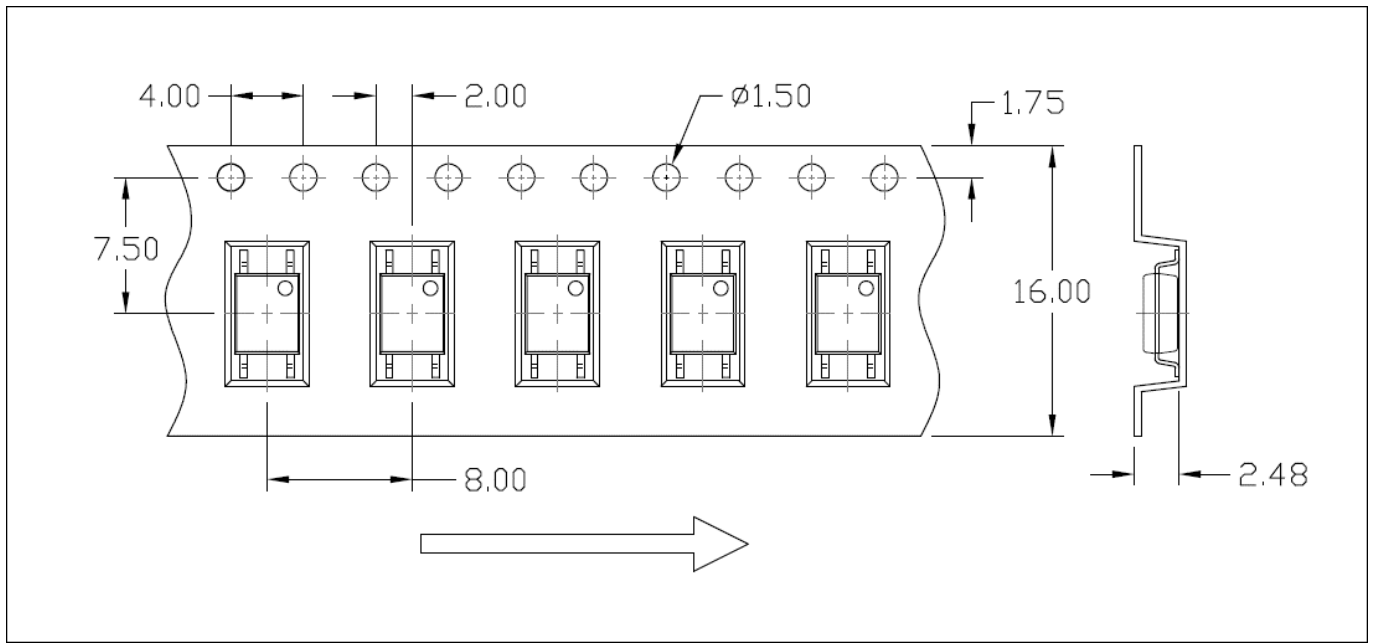


**) ecommended Solder Ma\$2 (Dimension\$ in mm & nle\$\$ other / i\$e \$tated=**

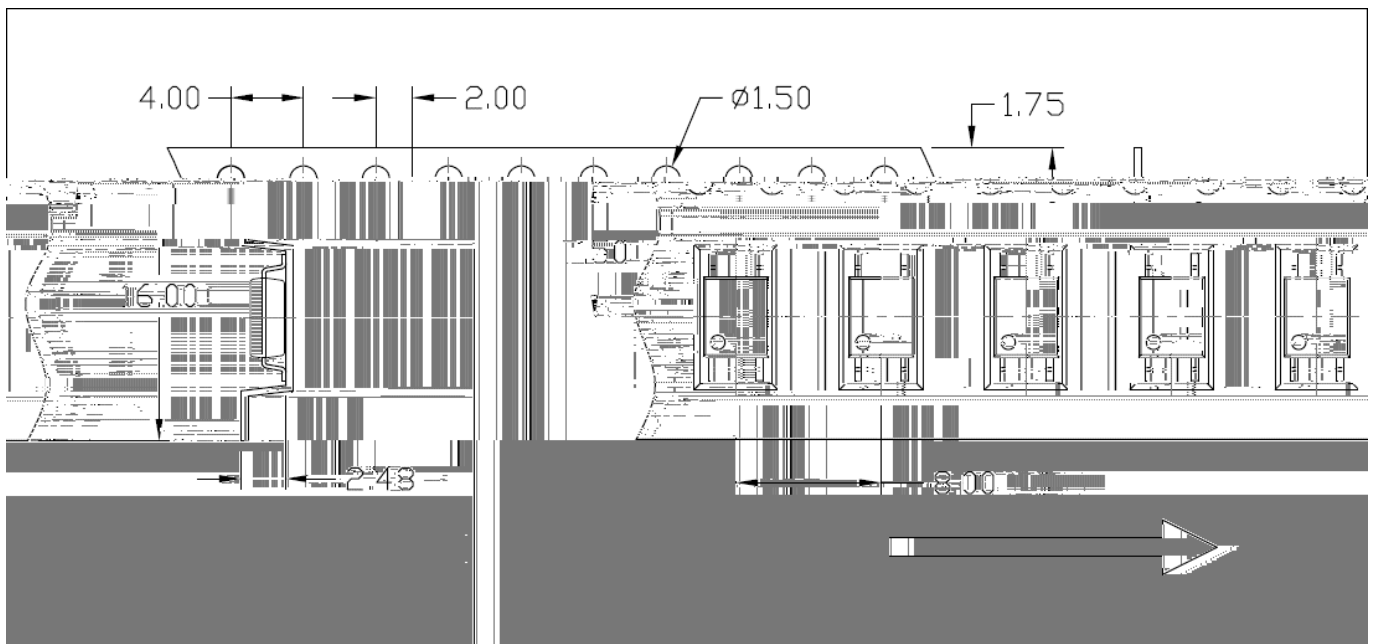


**CA ) IE ) TAPE SPECIFICATIONS (Dimension\$ in mm &nle\$\$ other / i\$e \$tated=**

**O%tion T1**



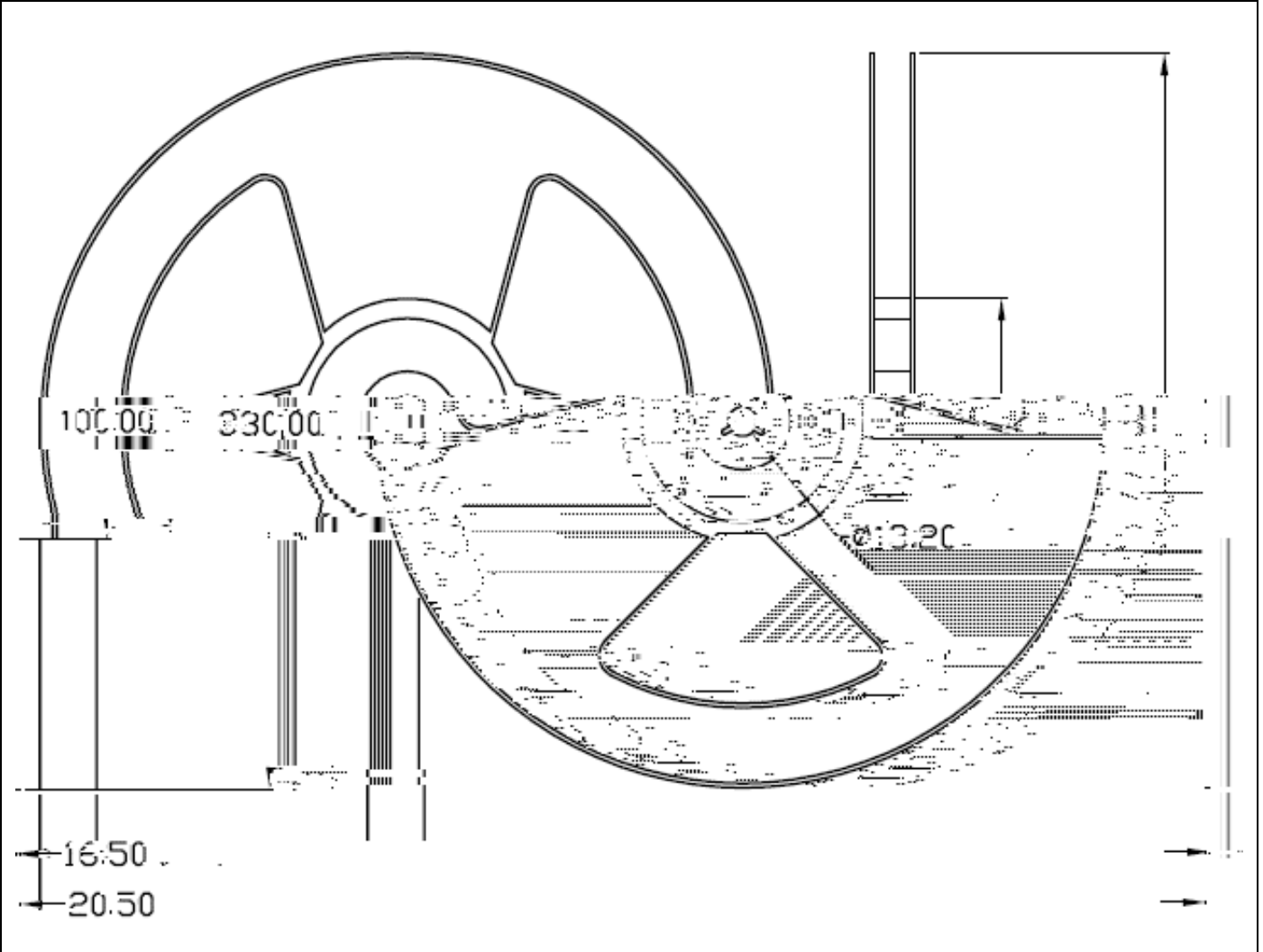
**O%tion T2**





**) EE# SPECIFICATIONS (Dimension\$ in mm &nle\$\$ other / i\$e \$tated=**

O%tion T1 > T2





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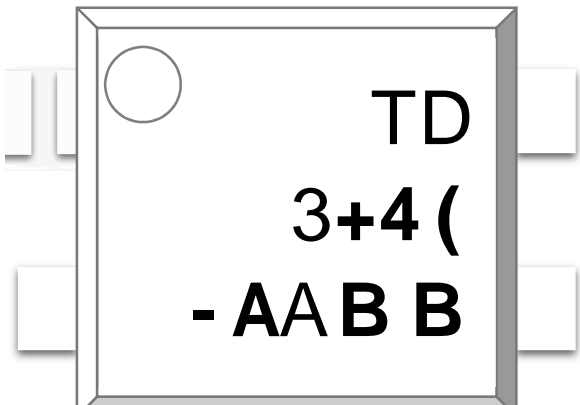
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**OPERATIONAL AND MANUFACTURING INFORMATION**

**MANUFACTURING INFORMATION**

|   |   |
|---|---|
|  | <p>TD      @ Component</p> <p>3+4    @ Part Number</p> <p>(       @ CT )</p> <p>-       @ - Designation</p> <p>A       @ Fiscal Area</p> <p>A       @ Manufacturing Code</p> <p>BB     @ Board Bee2</p> |
|---|---|

**OPERATIONAL INFORMATION**

**ASSEMBLY INFORMATION**

|                              |  |
|------------------------------|--|
| <p><b>TD3+4 (CD=3! -</b></p> | <div style="border: 1px solid black; padding: 5px;">  <p><b>福建天电光电有限公司</b><br/>FUJIAN LIGHTNING OPTOELECTRONIC CO., LTD.</p> <p>Part No : XXXXXXXXXXXX      Bin Code : X</p>  <p>Lot No : XXXXXXXXXXXX</p> <p>Date Code : XXXX</p> <p>Q'ty : XXXX pcs</p>    </div> |
|------------------------------|--|

**PACKING INFORMATION**

| Option | Quantity | Quantity Inner 10? | Quantity Outer 10? |
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